

CALL FOR PAPERS:

THERMAL INNOVATION FOR MODERN TECHNOLOGY

TWO-PAGE ABSTRACTS DUE OCTOBER 5

SEMI-THERM invites authors to submit a two-page abstract showcasing research, technologies, and ideas advancing thermal management.

Selected authors will present as part of the conference technical program to a global audience of engineers, researchers, professors, and technology developers, with accepted papers published in IEEE Xplore and the SEMI-THERM Technical Library.

RESEARCH DRIVING INNOVATION

- Thermal technologies for advanced semiconductor packaging (2.5D, 3D, HI, chiplets, HBM) and microelectronics
- Advanced cooling for data centers, AI infrastructure and power electronics
- Photonics and co-packaged optics
- New thermal challenges in AI, 5G/6G and edge hardware
- Energy efficiency and sustainability in thermal design
- Two-phase cooling innovations, immersion, passive and pumped systems
- Thermal design for aerospace, EVs and ruggedized systems
- Advanced thermal materials, TIMs and fabrication techniques
- Thermal measurement techniques, sensing and metrology
- CFD, digital twins, multiphysics simulation and thermo-mechanical reliability modeling
- Machine learning and AI-driven thermal analysis



Author Information &
Submission Guidelines



Abstract Submission

IMPORTANT DATES

Two-Page Abstract Submission
October 5, 2026

Paper Acceptance Notification
November 9, 2026

Draft or Peer Reviewed Manuscripts Due
December 7, 2026

Conference Registration Deadline
January 11, 2027

Final Paper Submission
January 25, 2027

REGISTRATION FEES

Presenter Rate	\$875
Student Presenter Rate	\$525*
Standard Conference Rate	\$1575
Student Conference Rate	\$525

*Scholarships available for student presenters through the Thermal Futures Initiative.

PAPER FORMATS

Peer Reviewed
Non-Peer Reviewed
Presentation Only